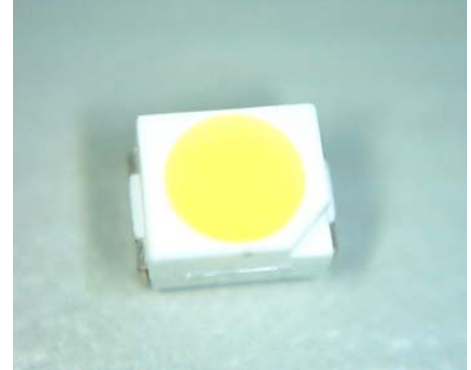


**Technical Data Sheet****White SMD Surface Mount Device****67-23UTC/S400-XX/TR8****Features**

- Fluorescence Type
- High Luminous Intensity
- High Efficiency
- Emission Color:x=0.29,y=0.30
- Pb-free
- The product itself will remain within RoHS compliant version.

**Descriptions**

The white LED which was fabricated using a blue LED and a phosphor, and the phosphor is excited by blue light and emits yellow fluorescence. The mixture of blue light and yellow light results in a white emission.

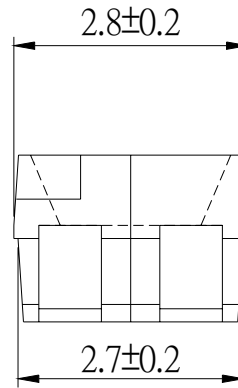
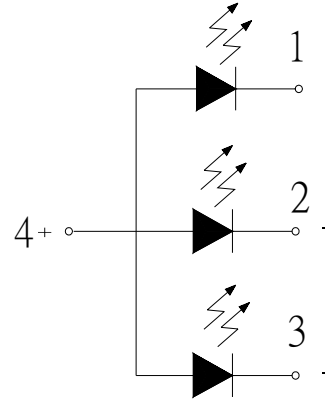
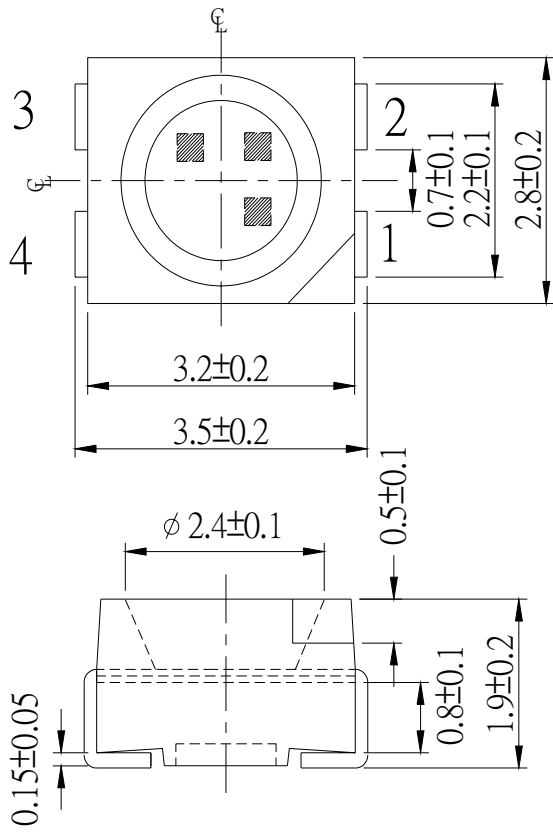
**Applications**

- OA Equipment
- Backlighting of Full Color LCD
- Automotive Equipment
- Replacement of Conventional Light Bulbs and Fluorescent Lamps

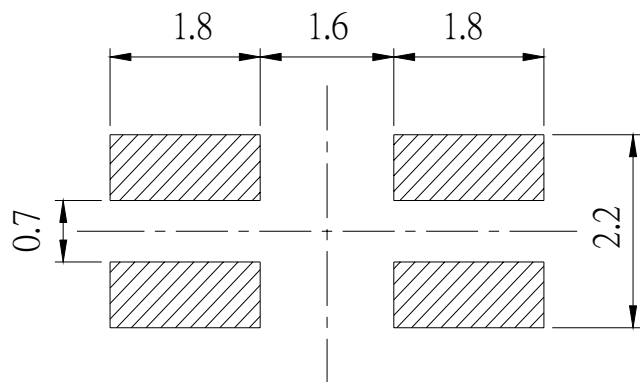
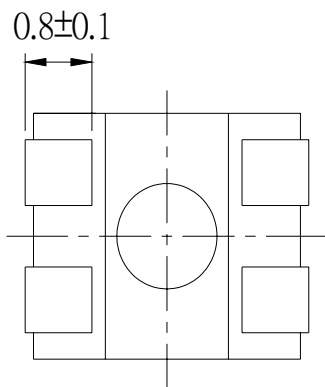
**Device Selection Guide**

Chip		Lens Color
Material	Emitted Color	
InGaN	White	Water Clear

**Package Outline Dimensions**



For reflow soldering(propose)



**Note:** The tolerances unless mentioned is ±0.1mm ,Unit = mm

**67-23UTC/S400-XX/TR8**

**Absolute Maximum Ratings (Ta=25°C)**

Parameter	Symbol	Rating	Unit
Reverse Voltage*1	V <sub>R</sub>	5	V
Forward Current*1	I <sub>F</sub>	25	mA
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +90	°C
Electrostatic Discharge(HBM) *1	ESD	150	V
Power Dissipation*1	P <sub>d</sub>	100	mW
Peak Forward Current (Duty 1/10 @1KHz) *1	I <sub>FP</sub>	100	mA
Soldering Temperature	T <sub>sol</sub>	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

\*. Maximum forward current for each die.

**Electro-Optical Characteristics (Ta=25°C)**

Parameter	Symbol	*1 Chip Rank	Min.	Typ.	Max.	Units	Condition
Luminous Intensity*2	I <sub>V</sub>	X8	850	1700	--	mcd	I <sub>F</sub> =20mA*3
		X9	1045	1900			I <sub>F</sub> =20mA*3
Forward Voltage*3	V <sub>F</sub>	--	--	3.5	4.0	V	I <sub>F</sub> =20mA
Reverse Current*3	I <sub>R</sub>	--	--	--	50	μA	V <sub>R</sub> =5V
Viewing Angle	2θ 1/2	--	--	120	--	deg	I <sub>F</sub> =20mA
Chromaticity*4	x	--	--	0.29	--	--	I <sub>F</sub> =20mA
Coordinates*4	y	--	--	0.30	--	--	I <sub>F</sub> =20mA

\*1 67-23UTC/S400-XX/TR8

 Chip Rank

\*2 When three LED dies are operated simultaneously.

\*3 For each die.

\*4 The C.I.E. 1931 chromaticity diagram.

The products are sensitive to static electricity and care must be fully taken when handling products.

**67-23UTC/S400-XX/TR8**

**Color Ranks**

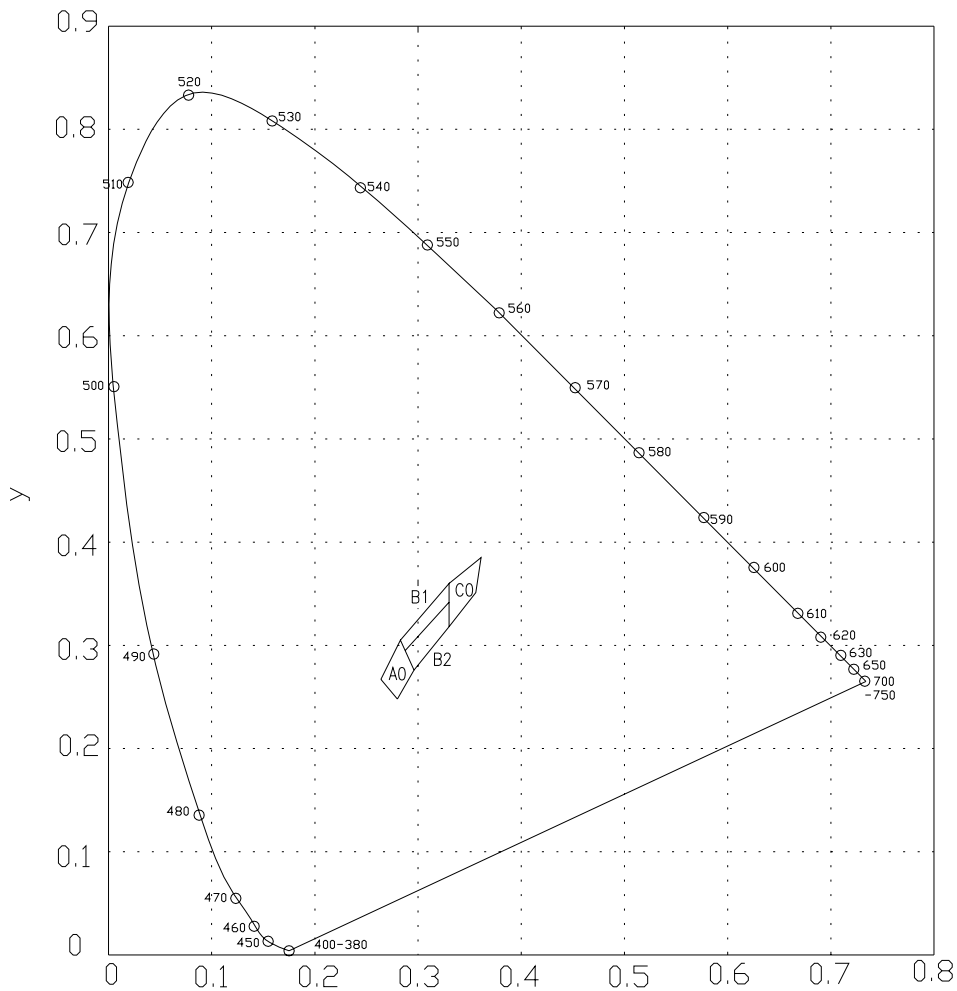
	Rank A0			
x	0.280	0.264	0.283	0.296
y	0.248	0.267	0.305	0.276

	Rank B1			
x	0.287	0.283	0.330	0.330
y	0.295	0.305	0.360	0.339

	Rank B2			
x	0.296	0.287	0.330	0.330
y	0.276	0.295	0.339	0.318

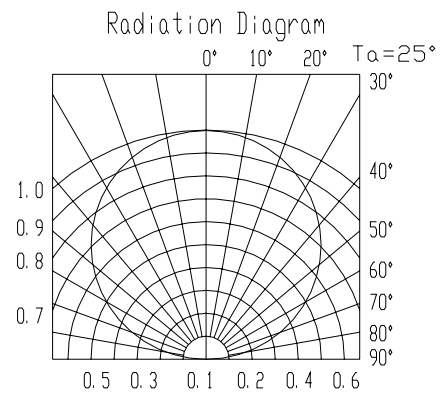
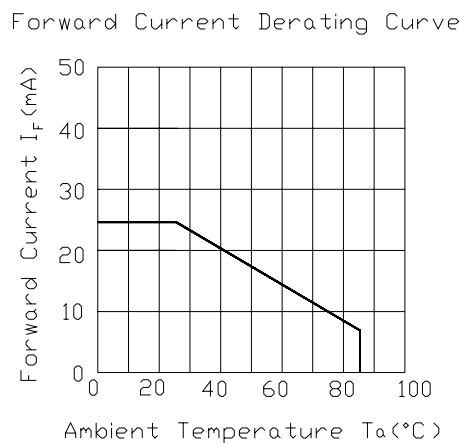
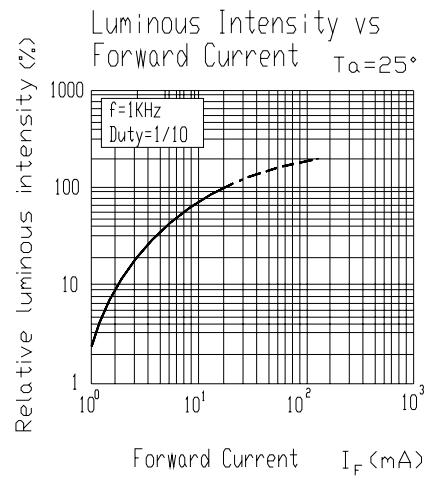
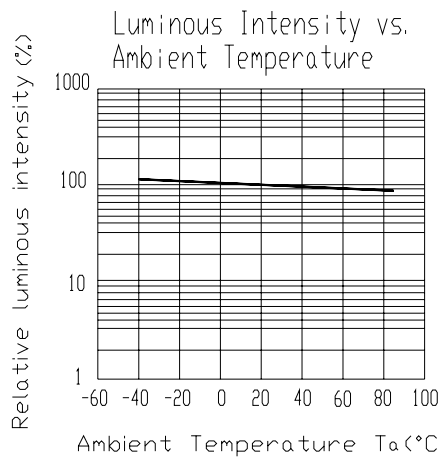
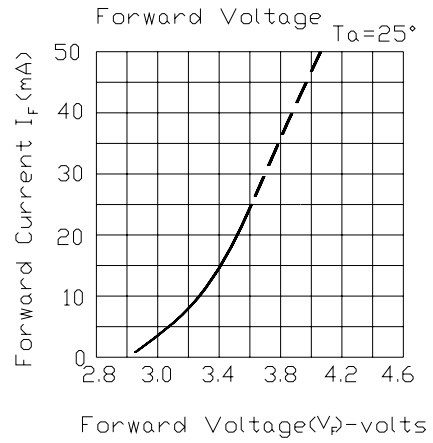
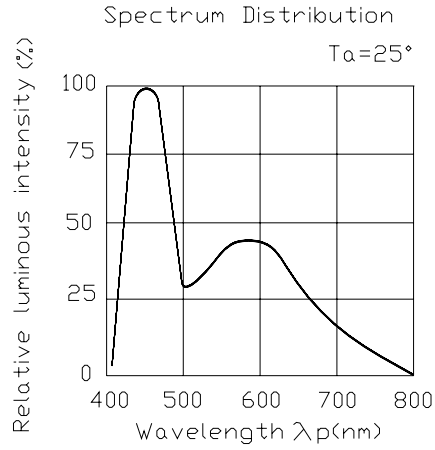
	Rank C0			
x	0.330	0.330	0.361	0.356
y	0.318	0.360	0.385	0.351

**CIE Chromaticity Diagram**



\*The C.I.E. 1931 color rank ( Tolerance  $\pm 0.01$ ).

**Typical Electro-Optical Characteristics Curves**

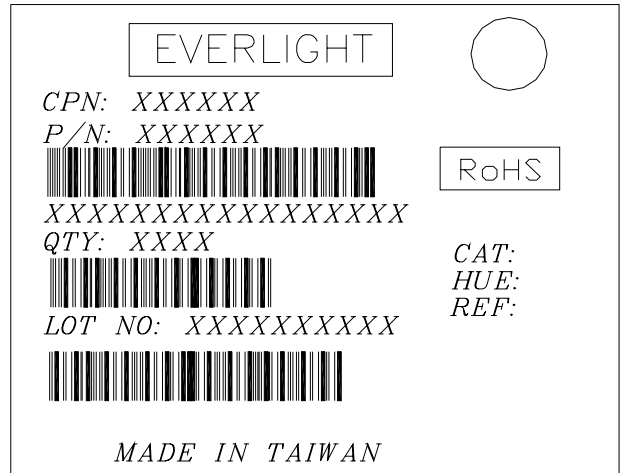


**Label explanation**

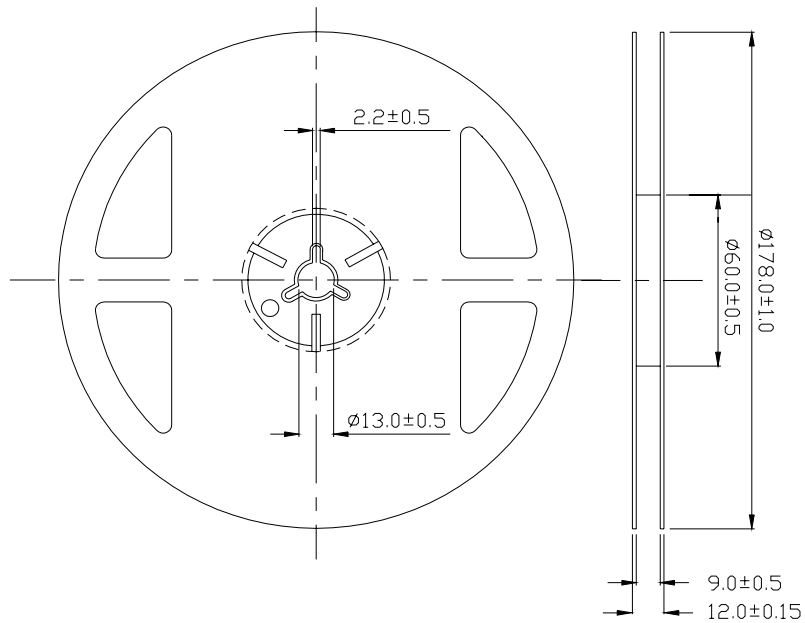
**CAT: Luminous Intensity Rank**

**HUE: Chromaticity Coordinates**

**REF: Forward Voltage Rank**



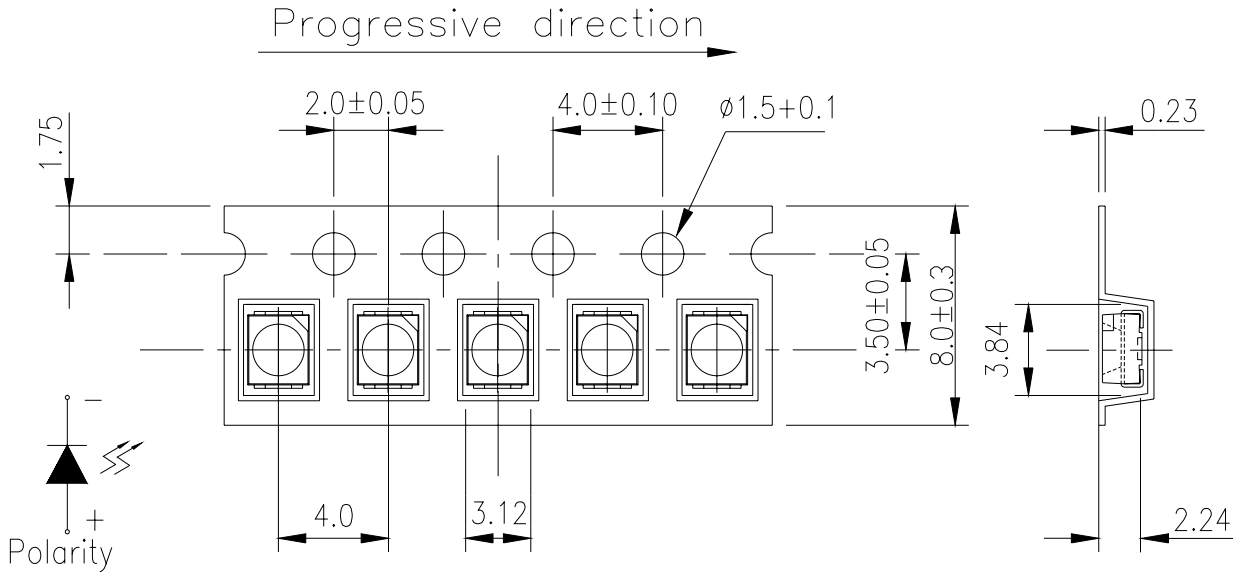
**Reel Dimensions**



**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$  ,Unit = mm

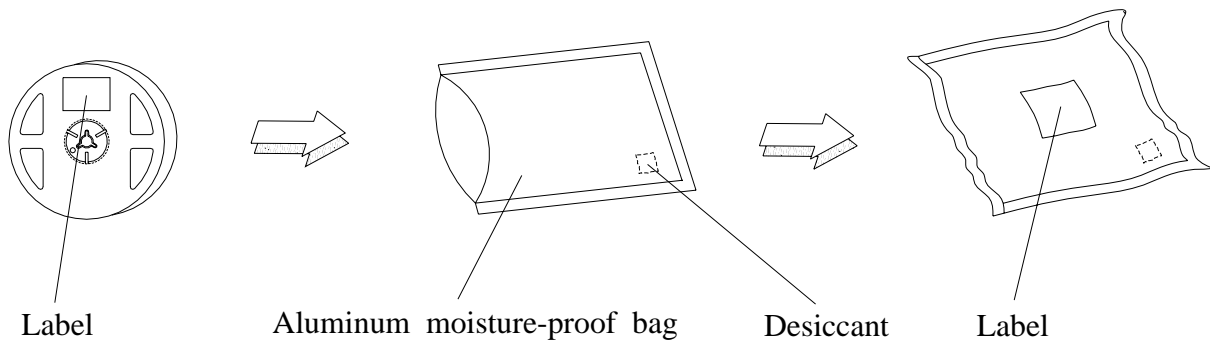
**67-23UTC/S400-XX/TR8**

**Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel.**



**Note:** Tolerances Unless Dimension  $\pm 0.1\text{mm}$  , Unit = mm

**Moisture Resistant Packaging**



**67-23UTC/S400-XX/TR8**

**Reliability Test Items And Conditions**

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C ±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min § 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min § 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	IF = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1



**Precautions For Use**

## 1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change ( Burn out will happen ).

## 2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30 deg C or less and 60% RH or less.

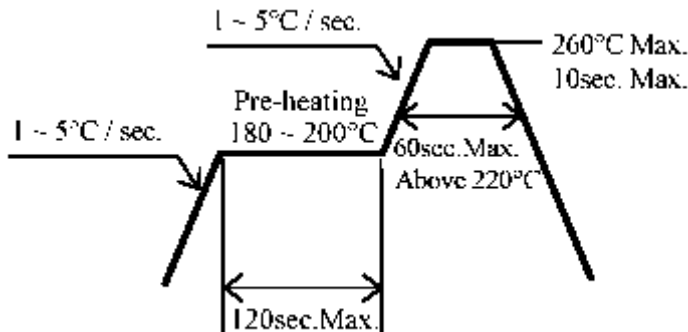
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment :  $60\pm 5^{\circ}\text{C}$  for 24 hours.

## 3. Soldering Condition

## 3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

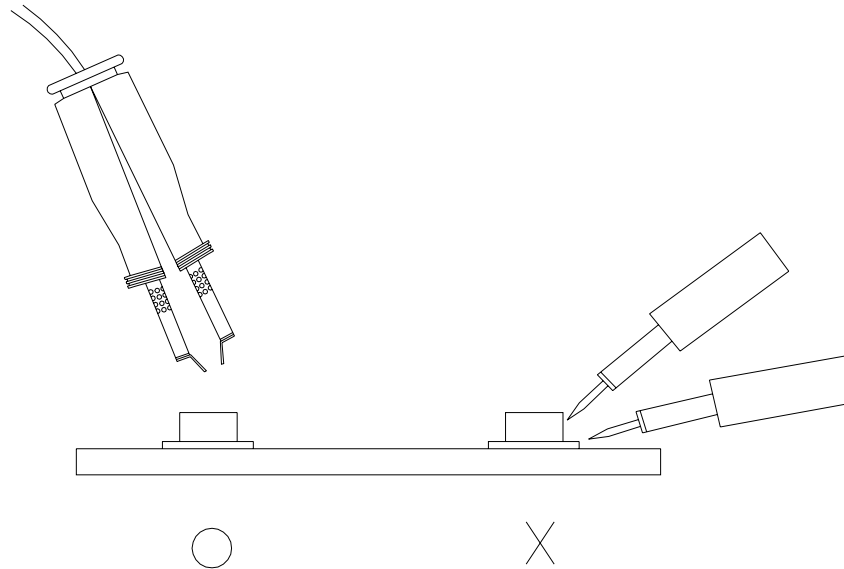
3.4 After soldering, do not warp the circuit board.

## 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

**5.Repairing**

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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